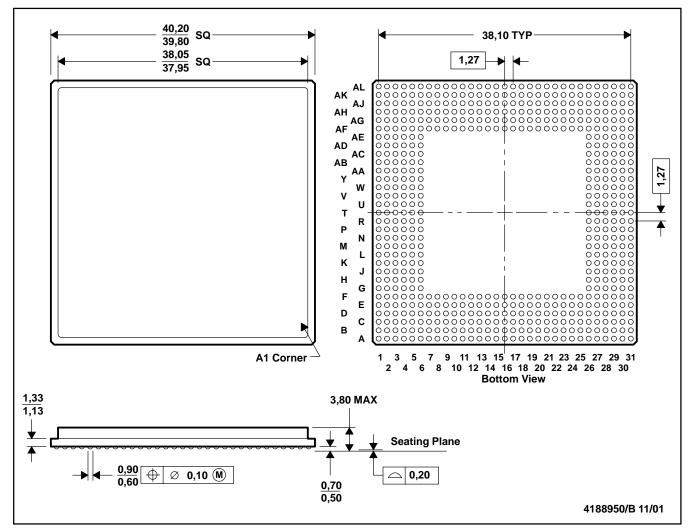
MECHANICAL DATA

MPBG116A - MAY 1999 - REVISED JANUARY 2002

PLASTIC BALL GRID ARRAY

GJT (S-PBGA-N600)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Flip chip application only



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